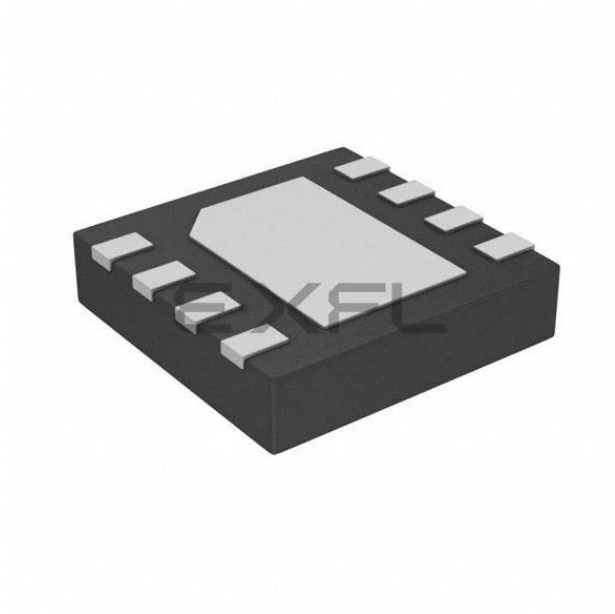

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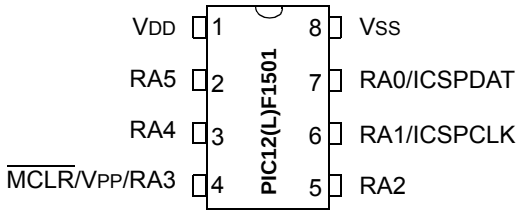
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f1501t-i-mf

PIN DIAGRAMS

8-pin PDIP, SOIC, MSOP, DFN, UDFN



Note: See Table 1 for location of all peripheral functions.

TABLE 1-2: PIC12(L)F1501 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/C1IN+/DACOUT1/ CWG1B(1)/CLC2IN1/PWM2/ ICSPDAT	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	A/D Channel input.
	C1IN+	AN	—	Comparator positive input.
	DACOUT1	—	AN	Digital-to-Analog Converter output.
	CWG1B	—	CMOS	CWG complementary output.
	CLC2IN1	ST	—	Configurable Logic Cell source input.
	PWM2	—	CMOS	Pulse Width Module source output.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
RA1/AN1/VREF+/C1IN0-/ NCO1(1)/CLC2IN0/ICSPCLK	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	A/D Channel input.
	VREF+	AN	—	A/D Positive Voltage Reference input.
	C1IN0-	AN	—	Comparator negative input.
	NCO1	—	CMOS	Numerically Controlled Oscillator output.
	CLC2IN0	ST	—	Configurable Logic Cell source input.
	ICSPCLK	ST	—	ICSP™ Programming Clock.
RA2/AN2/C1OUT/DACOUT2/ T0CKI/INT/PWM1/CLC1(1)/ CWG1A(1)/$\overline{\text{CWG1FLT}}$	RA2	ST	CMOS	General purpose I/O.
	AN2	AN	—	A/D Channel input.
	C1OUT	—	CMOS	Comparator output.
	DACOUT2	—	AN	Digital-to-Analog Converter output.
	T0CKI	ST	—	Timer0 clock input.
	INT	ST	—	External interrupt.
	PWM1	—	CMOS	Pulse Width Module source output.
	CLC1	—	CMOS	Configurable Logic Cell source output.
	CWG1A	—	CMOS	CWG complementary output.
	$\overline{\text{CWG1FLT}}$	ST	—	Complementary Waveform Generator Fault input.
RA3/CLC1IN0/VPP/T1G(1)/$\overline{\text{MCLR}}$	RA3	TTL	—	General purpose input.
	CLC1IN0	ST	—	Configurable Logic Cell source input.
	VPP	HV	—	Programming voltage.
	T1G	ST	—	Timer1 Gate input.
	$\overline{\text{MCLR}}$	ST	—	Master Clear with internal pull-up.
RA4/AN3/C1IN1-/CWG1B(1)/ CLC1(1)/PWM3/CLKOUT/T1G(1)	RA4	TTL	CMOS	General purpose I/O.
	AN3	AN	—	A/D Channel input.
	C1IN1-	AN	—	Comparator negative input.
	CWG1B	—	CMOS	CWG complementary output.
	CLC1	—	CMOS	Configurable Logic Cell source output.
	PWM3	—	CMOS	Pulse Width Module source output.
	CLKOUT	—	CMOS	FOSC/4 output.
	T1G	ST	—	Timer1 Gate input.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C™ = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Alternate pin function selected with the APFCON (Register 11-1) register.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Banks 14-29											
x0Ch/ x8Ch — x1Fh/ x9Fh	—	Unimplemented								—	—
Bank 30											
F0Ch to F0Eh	—	Unimplemented								—	—
F0Fh	CLCDATA	—	—	—	—	—	—	MLC2OUT	MLC1OUT	---- --00	---- --00
F10h	CLC1CON	LC1EN	LC1OE	LC1OUT	LC1INTP	LC1INTN	LC1MODE<2:0>			0000 0000	0000 0000
F11h	CLC1POL	LC1POL	—	—	—	LC1G4POL	LC1G3POL	LC1G2POL	LC1G1POL	0--- xxxx	0--- uuuu
F12h	CLC1SEL0	—	LC1D2S<2:0>			—	LC1D1S<2:0>			-xxx -xxx	-uuu -uuu
F13h	CLC1SEL1	—	LC1D4S<2:0>			—	LC1D3S<2:0>			-xxx -xxx	-uuu -uuu
F14h	CLC1GLS0	LC1G1D4T	LC1G1D4N	LC1G1D3T	LC1G1D3N	LC1G1D2T	LC1G1D2N	LC1G1D1T	LC1G1D1N	xxxx xxxx	uuuu uuuu
F15h	CLC1GLS1	LC1G2D4T	LC1G2D4N	LC1G2D3T	LC1G2D3N	LC1G2D2T	LC1G2D2N	LC1G2D1T	LC1G2D1N	xxxx xxxx	uuuu uuuu
F16h	CLC1GLS2	LC1G3D4T	LC1G3D4N	LC1G3D3T	LC1G3D3N	LC1G3D2T	LC1G3D2N	LC1G3D1T	LC1G3D1N	xxxx xxxx	uuuu uuuu
F17h	CLC1GLS3	LC1G4D4T	LC1G4D4N	LC1G4D3T	LC1G4D3N	LC1G4D2T	LC1G4D2N	LC1G4D1T	LC1G4D1N	xxxx xxxx	uuuu uuuu
F18h	CLC2CON	LC2EN	LC2OE	LC2OUT	LC2INTP	LC2INTN	LC2MODE<2:0>			0000 0000	0000 0000
F19h	CLC2POL	LC2POL	—	—	—	LC2G4POL	LC2G3POL	LC2G2POL	LC2G1POL	0--- xxxx	0--- uuuu
F1Ah	CLC2SEL0	—	LC2D2S<2:0>			—	LC2D1S<2:0>			-xxx -xxx	-uuu -uuu
F1Bh	CLC2SEL1	—	LC2D4S<2:0>			—	LC2D3S<2:0>			-xxx -xxx	-uuu -uuu
F1Ch	CLC2GLS0	LC2G1D4T	LC2G1D4N	LC2G1D3T	LC2G1D3N	LC2G1D2T	LC2G1D2N	LC2G1D1T	LC2G1D1N	xxxx xxxx	uuuu uuuu
F1Dh	CLC2GLS1	LC2G2D4T	LC2G2D4N	LC2G2D3T	LC2G2D3N	LC2G2D2T	LC2G2D2N	LC2G2D1T	LC2G2D1N	xxxx xxxx	uuuu uuuu
F1Eh	CLC2GLS2	LC2G3D4T	LC2G3D4N	LC2G3D3T	LC2G3D3N	LC2G3D2T	LC2G3D2N	LC2G3D1T	LC2G3D1N	xxxx xxxx	uuuu uuuu
F1Fh	CLC2GLS3	LC2G4D4T	LC2G4D4N	LC2G4D3T	LC2G4D3N	LC2G4D2T	LC2G4D2N	LC2G4D1T	LC2G4D1N	xxxx xxxx	uuuu uuuu
F20h to F6Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved. Shaded locations are unimplemented, read as '0'.
Note 1: PIC12F1501 only.
2: Unimplemented, read as '1'.

REGISTER 7-4: PIE3: PERIPHERAL INTERRUPT ENABLE REGISTER 3

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
—	—	—	—	—	—	CLC2IE	CLC1IE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

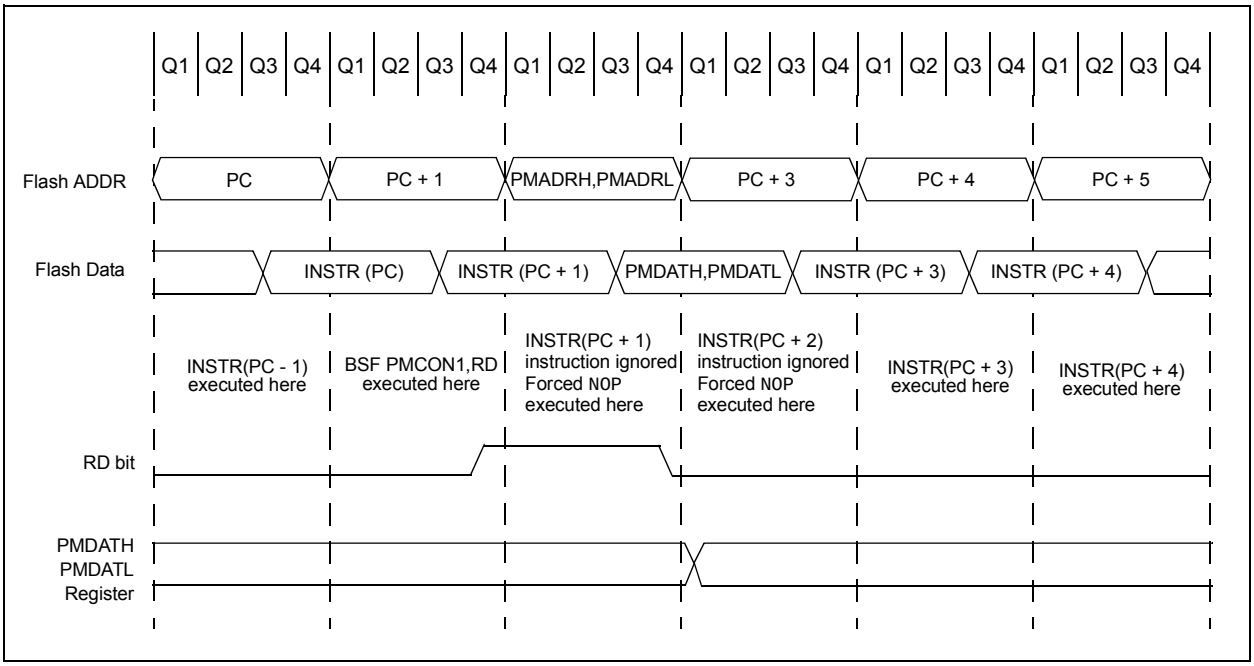
bit 7-2 **Unimplemented:** Read as '0'

bit 1 **CLC2IE:** Configurable Logic Block 2 Interrupt Enable bit
- 1 = Enables the CLC 2 interrupt
- 0 = Disables the CLC 2 interrupt

bit 0 **CLC1IE:** Configurable Logic Block 1 Interrupt Enable bit
- 1 = Enables the CLC 1 interrupt
- 0 = Disables the CLC 1 interrupt

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

FIGURE 10-2: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



EXAMPLE 10-1: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI : PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select Bank for PMCON registers
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWF    PMADRH           ; Store MSB of address

    BCF      PMCON1,CFGS      ; Do not select Configuration Space
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Ignored (Figure 10-2)
    NOP                       ; Ignored (Figure 10-2)

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

TABLE 12-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPT-ON-CHANGE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	99
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	64
IOCAF	—	—	IOCAF5	IOCAF4	IOCAF3	IOCAF2	IOCAF1	IOCAF0	103
IOCAN	—	—	IOCAN5	IOCAN4	IOCAN3	IOCAN2	IOCAN1	IOCAN0	103
IOCAP	—	—	IOCAP5	IOCAP4	IOCAP3	IOCAP2	IOCAP1	IOCAP0	103
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA2	TRISA1	TRISA0	98

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupt-on-change.
Note 1: Unimplemented, read as '1'.

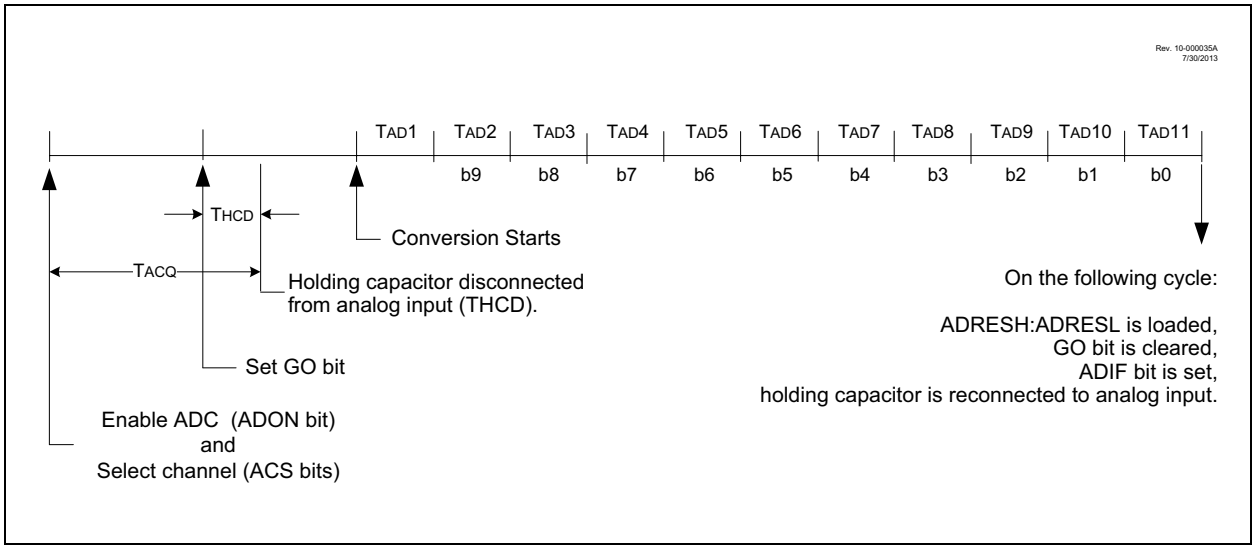
TABLE 15-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})				
ADC Clock Source	**ADCS<2:0>**	**20 MHz**	**16 MHz**	**8 MHz**	**4 MHz**	**1 MHz**
Fosc/2	000	100 ns	125 ns	250 ns	500 ns	2.0 μs
Fosc/4	100	200 ns	250 ns	500 ns	1.0 μs	4.0 μs
Fosc/8	001	400 ns	500 ns	1.0 μs	2.0 μs	8.0 μs
Fosc/16	101	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs
Fosc/32	010	1.6 μs	2.0 μs	4.0 μs	8.0 μs	32.0 μs
Fosc/64	110	3.2 μs	4.0 μs	8.0 μs	16.0 μs	64.0 μs
FRC	x11	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs

Legend: Shaded cells are outside of recommended range.

Note: The T_{AD} period when using the FRC clock source can fall within a specified range, (see T_{AD} parameter). The T_{AD} period when using the F_{OSC}-based clock source can be configured for a more precise T_{AD} period. However, the FRC clock source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 15-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES



REGISTER 15-4: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<9:2>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **ADRES<9:2>**: ADC Result Register bits
Upper eight bits of 10-bit conversion result

REGISTER 15-5: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<1:0>		—	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **ADRES<1:0>**: ADC Result Register bits
Lower two bits of 10-bit conversion result

bit 5-0 **Reserved**: Do not use.

LSLF **Logical Left Shift**

Syntax: [*label*] LSLF f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<7>) → C
(f<6:0>) → dest<7:1>
0 → dest<0>

Status Affected: C, Z

Description: The contents of register 'f' are shifted one bit to the left through the Carry flag. A '0' is shifted into the LSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.

LSRF **Logical Right Shift**

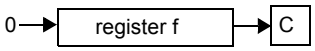
Syntax: [*label*] LSRF f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: 0 → dest<7>
(f<7:1>) → dest<6:0>,
(f<0>) → C,

Status Affected: C, Z

Description: The contents of register 'f' are shifted one bit to the right through the Carry flag. A '0' is shifted into the MSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.



MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Description: The contents of register f is moved to a destination dependent upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

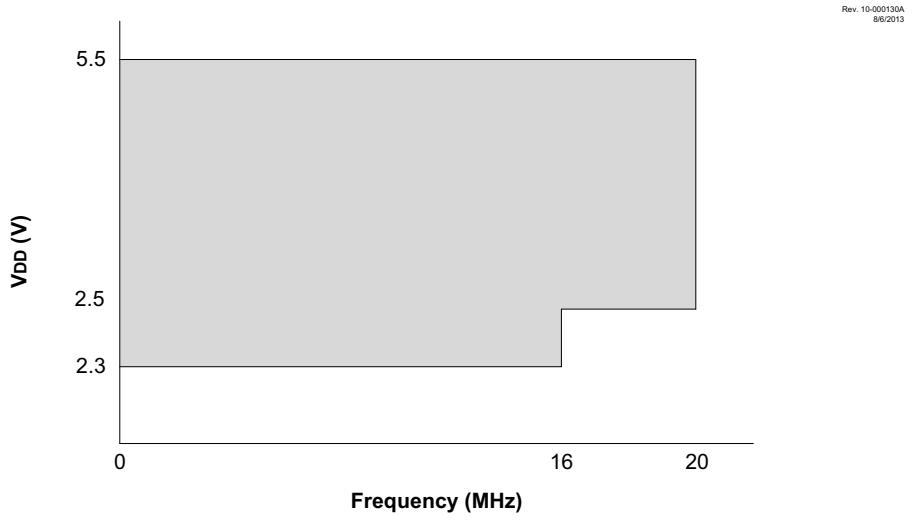
Cycles: 1

Example:

```
MOVF    FSR, 0
```

After Instruction
W = value in FSR register
Z = 1

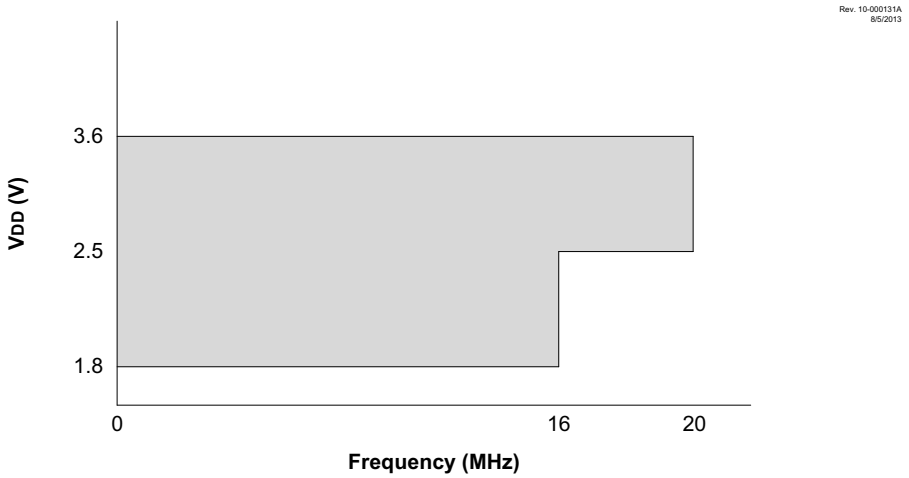
FIGURE 27-1: VOLTAGE FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C, PIC12F1501 ONLY



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: Refer to Table 27-8 for each Oscillator mode's supported frequencies.

FIGURE 27-2: VOLTAGE FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C, PIC12LF1501 ONLY



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: Refer to Table 27-8 for each Oscillator mode's supported frequencies.

TABLE 27-2: SUPPLY CURRENT (I_{DD})(1,2) (CONTINUED)

PIC12LF1501		Standard Operating Conditions (unless otherwise stated)					
PIC12F1501							
Param. No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D019C		—	1030	1500	µA	3.0	F_{OSC} = 20 MHz, External Clock (ECH), High-Power mode
D019C		—	1060	1600	µA	3.0	F_{OSC} = 20 MHz, External Clock (ECH), High-Power mode
		—	1220	1800	µA	5.0	
D019A		—	6	16	µA	1.8	F_{OSC} = 32 kHz, External Clock (ECL), Low-Power mode
		—	8	22	µA	3.0	
D019A		—	13	28	µA	2.3	F_{OSC} = 32 kHz, External Clock (ECL), Low-Power mode
		—	15	31	µA	3.0	
		—	16	36	µA	5.0	
D019B		—	19	35	µA	1.8	F_{OSC} = 500 kHz, External Clock (ECL), Low-Power mode
		—	32	55	µA	3.0	
D019B		—	31	52	µA	2.3	F_{OSC} = 500 kHz, External Clock (ECL), Low-Power mode
		—	38	65	µA	3.0	
		—	44	74	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{SS}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

TABLE 27-3: POWER-DOWN CURRENTS (I_{PD})(1,2) (CONTINUED)

PIC12LF1501		Operating Conditions: (unless otherwise stated) Low-Power Sleep Mode						
PIC12F1501		Low-Power Sleep Mode, VREGPM = 1						
Param. No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
D026		—	0.11	1.5	9.0	µA	1.8	ADC Current **(Note 3)**, No conversion in progress
		—	0.12	2.7	12	µA	3.0	
D026		—	0.30	4.0	11	µA	2.3	ADC Current **(Note 3)**, No conversion in progress
		—	0.35	5.0	13	µA	3.0	
		—	0.45	8.0	16	µA	5.0	
D026A*		—	250	—	—	µA	1.8	ADC Current **(Note 3)**, Conversion in progress
		—	250	—	—	µA	3.0	
D026A*		—	280	—	—	µA	2.3	ADC Current **(Note 3)**, Conversion in progress
		—	280	—	—	µA	3.0	
		—	280	—	—	µA	5.0	
D027		—	7	22	25	µA	1.8	Comparator, CxSP = 0
		—	8	23	27	µA	3.0	
D027		—	17	35	37	µA	2.3	Comparator, CxSP = 0
		—	18	37	38	µA	3.0	
		—	19	38	40	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral Δ current can be determined by subtracting the base I_{PD} current from this limit. Max. values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.

3: ADC clock source is FRC.

27.4 AC Characteristics

Timing Parameter Symbology has been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

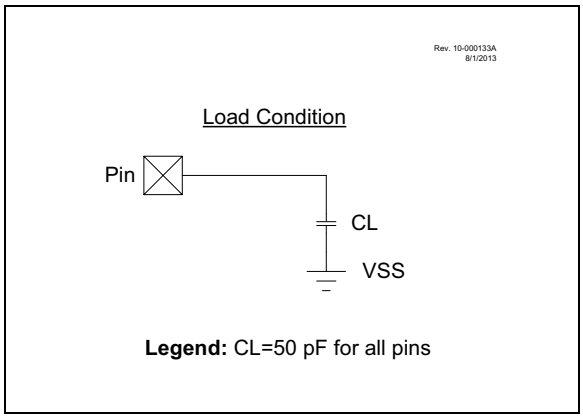
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	CLKIN
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDIx	sc	SCKx
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 27-4: LOAD CONDITIONS



Legend: CL=50 pF for all pins

FIGURE 28-17: IDD TYPICAL, HFINTOSC, PIC12LF1501 ONLY

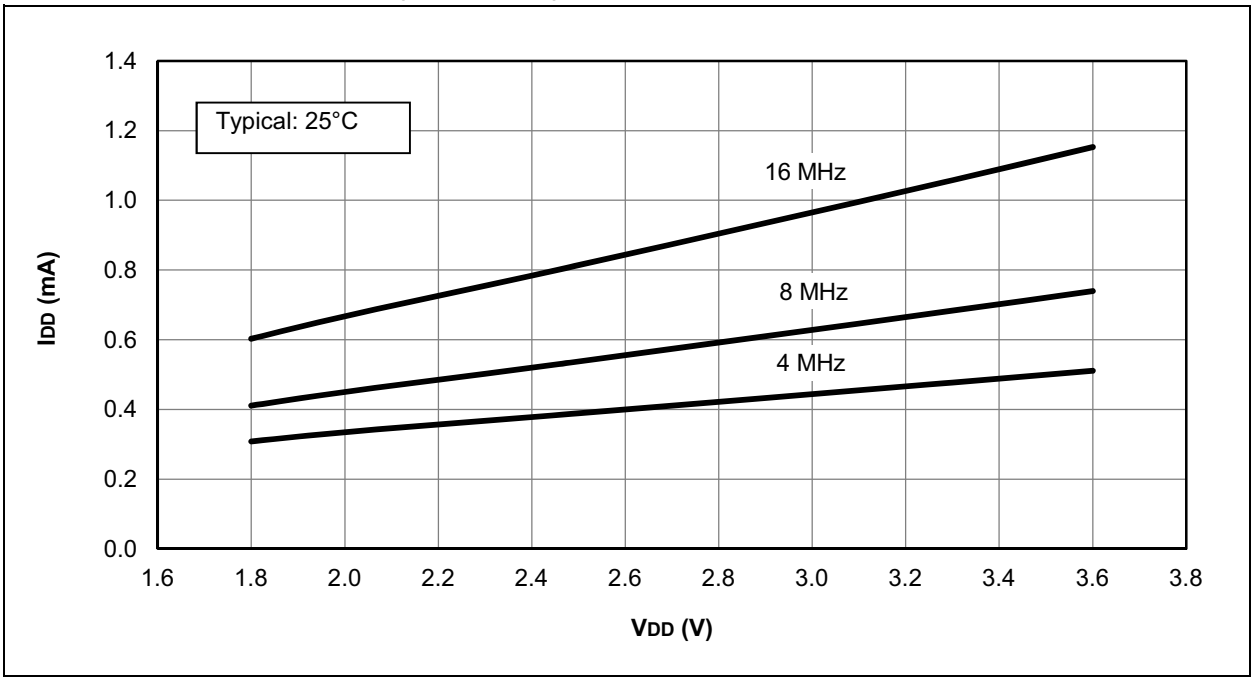


FIGURE 28-18: IDD MAXIMUM, HFINTOSC, PIC12LF1501 ONLY

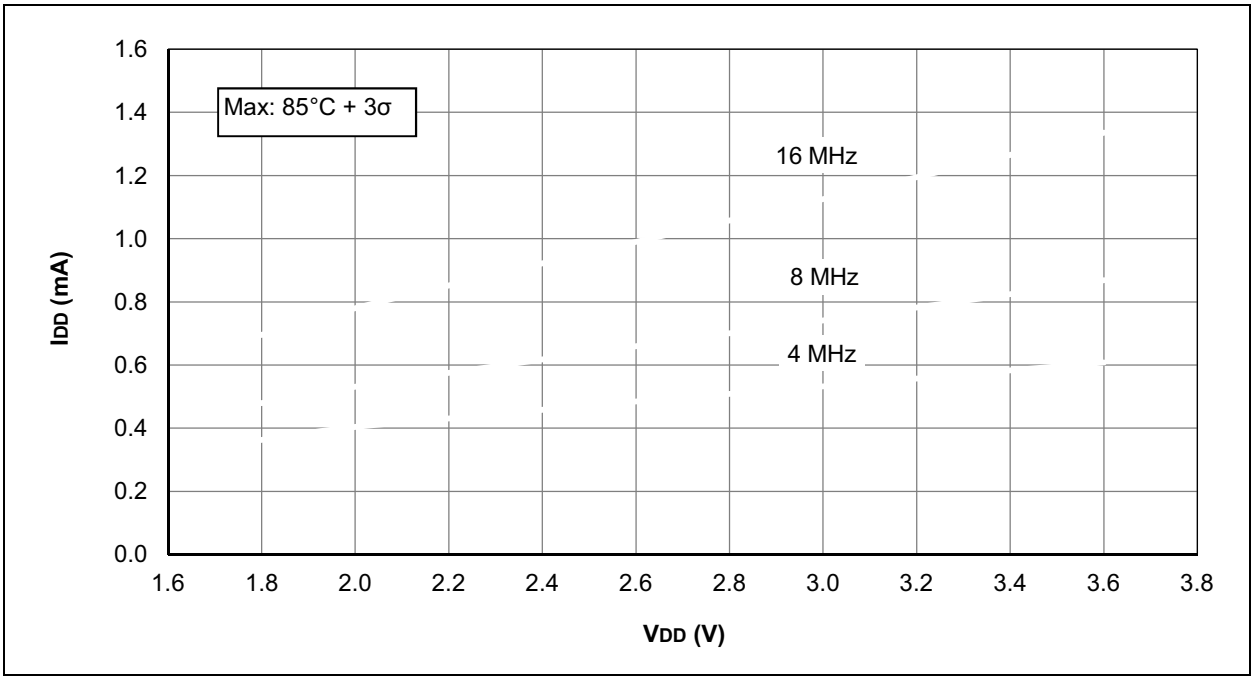


FIGURE 28-37: VOH vs. IOH OVER TEMPERATURE, VDD = 3.0V

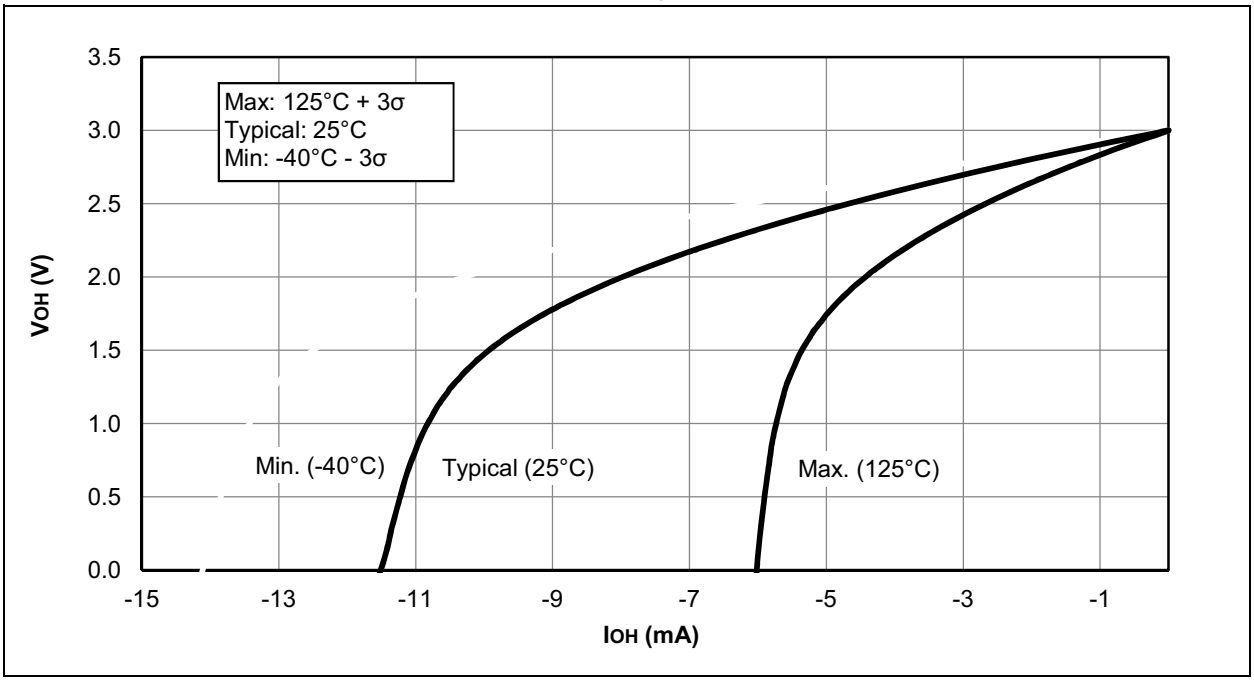


FIGURE 28-38: VOL vs. IOL OVER TEMPERATURE, VDD = 3.0V

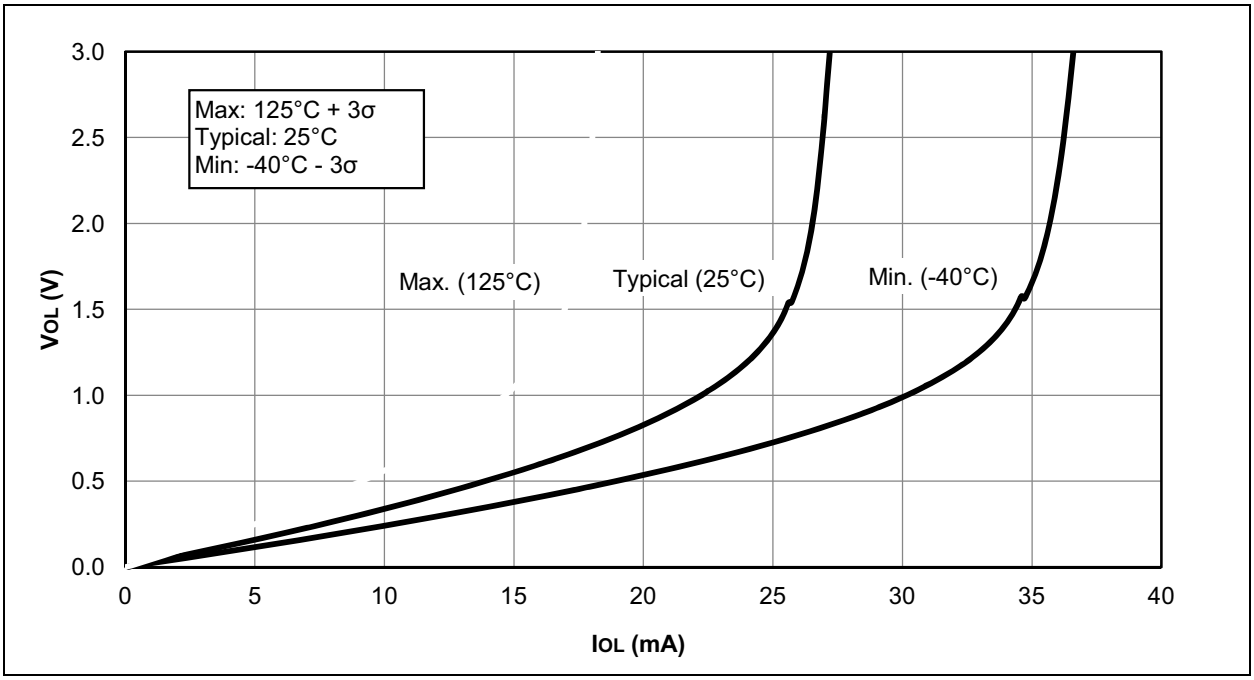


FIGURE 28-43: BROWN-OUT RESET VOLTAGE, BORV = 1, PIC12LF1501 ONLY

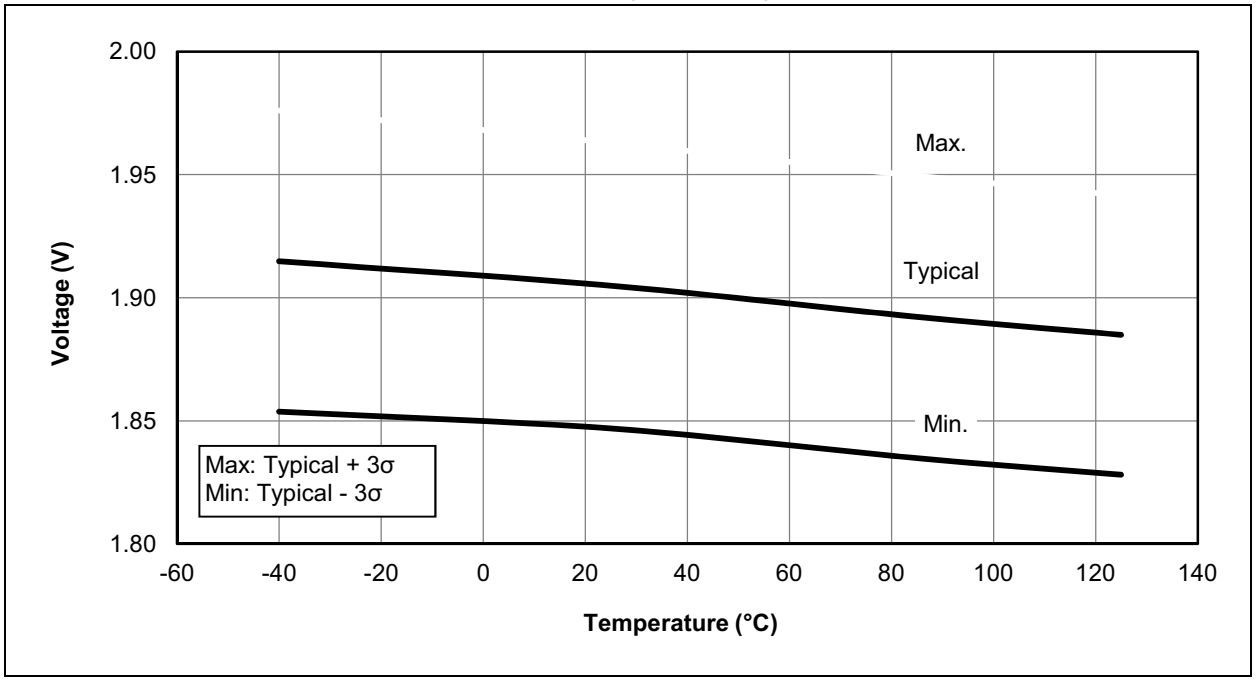
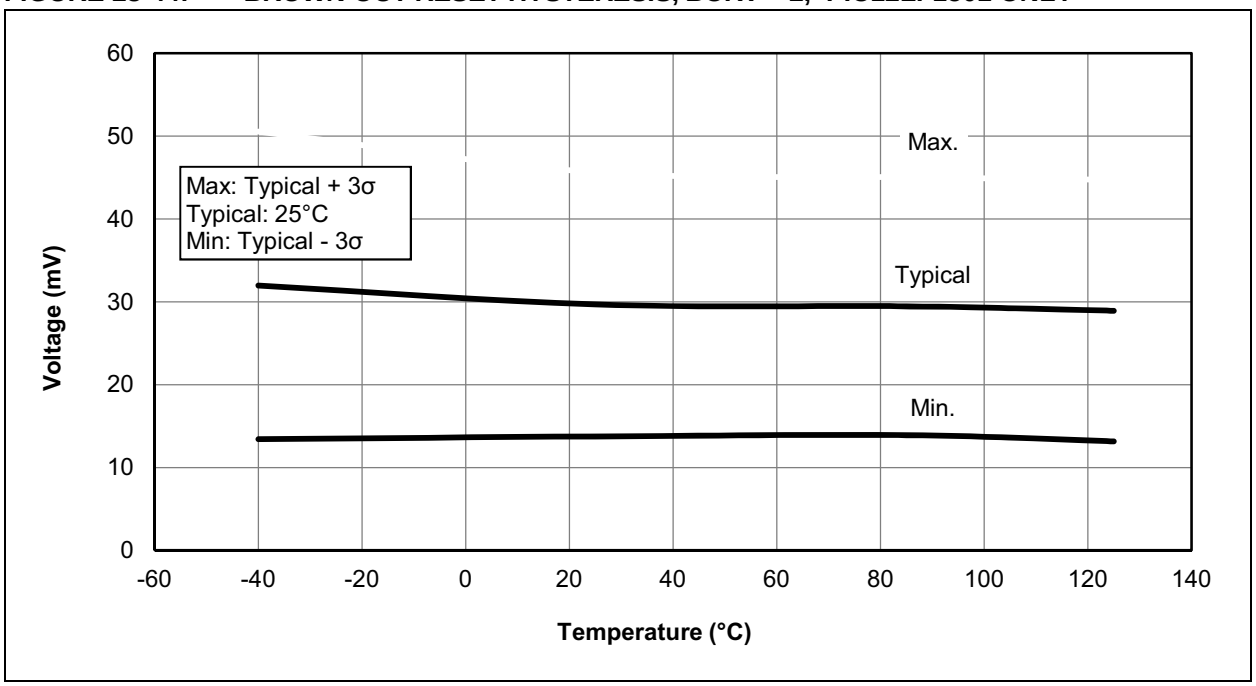


FIGURE 28-44: BROWN-OUT RESET HYSTERESIS, BORV = 1, PIC12LF1501 ONLY



29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

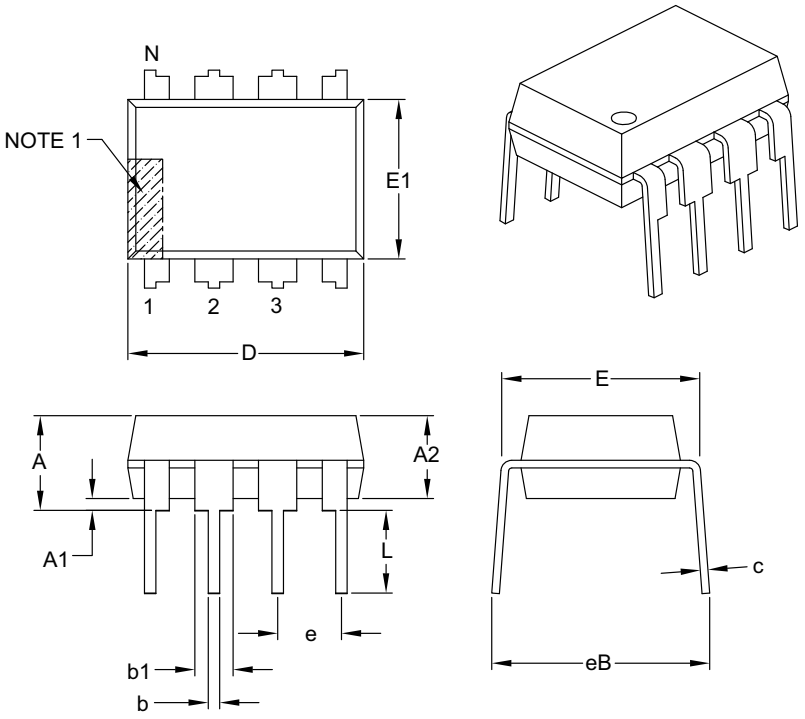
- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

30.2 Package Details

The following sections give the technical details of the packages.

8-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

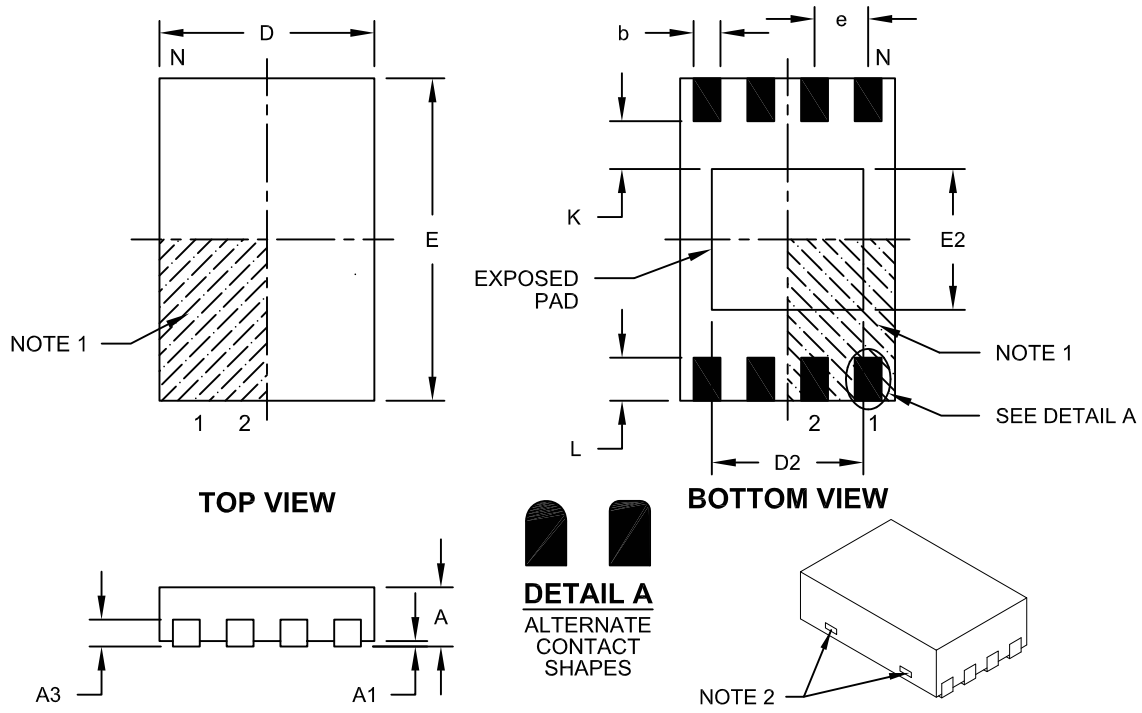
1. Pin 1 visual index feature may vary, but must be located with the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018B

8-Lead Plastic Dual Flat, No Lead Package (MU) – 2x3x0.5 mm Body [UDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1			0.07
Contact Thickness	A3		0.127 REF	
Overall Length	D	1.95	2.00	2.05
Overall Width	E	2.95	3.00	3.05
Exposed Pad Length	D2	1.30	1.40	1.50
Exposed Pad Width	E2	1.20	1.30	1.40
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.25	0.30	0.35
Contact-to-Exposed Pad	K		0.55 REF	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars at ends.
3. Package is saw singulated
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-136B

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